Beryllium Capsule Processing Improvements – Polishing and Mandrel Removal

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Beryllium has been of interest as an ablator but overall quality needs improvement

- Beryllium is a promising ablator material due to its low x-ray opacity, high tensile strength, and high thermal conductivity
- Beryllium capsule quality currently lags behind other ablators due to inner surface roughness, sphericity, argon content, crystallinity, etc.







The coating process produces rough capsules and they must be polished





The current polishing method utilizes a lapper





- Quick process (~3 days) but capsules can get stuck, producing facets
- Yield was ~50%
- Process has been improved by using different fixture/capsule slots as they wear down





The polishing process may introduce mid-mode roughening

Typical AFM Data of GDP Mandrel

Typical AFM Data of Polished Be Capsule



- Coating and polishing affect mid- and high-modes
- As-deposited capsules cannot be characterized with AFM due to high roughness



Wet tumble polishing is being explored as an alternative



- Two diamond slurries are used: 3-5 µm and 0-0.2 µm finishing slurry
- Can achieve <15 nm Ra surface roughness
- Shells cannot get stuck
- Ready for production qualification





Power spectra of test capsules do not change significantly in the mid-mode region





Current oxygen mandrel burnout causes inner surface defects



- Mandrels removed with oxygen at 380°C over 2-3 days
- Prior studies have shown temperature to be a strong driver for surface roughness



Concentration gradients can diffuse at oxygen mandrel removal conditions



 Problem has been solved for stepped dopant profiles but still relevant for concentration gradients

*Images taken from H. Huang's (GA) 54th annual APS DPP presentation



We are exploring ozone etching as an alternative mandrel removal method



 Hotfinger is held at 300°C while room temperature O₃/O₂ mixture flows over it

- $O_3 \lambda_{RT} = 3 \text{ days}, \lambda_{300^\circ C} = <1.5 \text{ sec}$

• Slower process – up to 2 weeks processing time



Current mandrel removal process can cause cracking in metal gradient Be capsules

X-Ray Image of Be/Cr Graded Capsule – Oxygen Burnout



X-Ray Image of Be/Cr Graded Keyhole Capsule – Ozone Burnout





Mass loss is similar between 10 µm and 15 µm drill holes



Results suggest reaction rate limitation







Ozone burnout sometimes leaves residue





Summary

Tumble polishing

 Cannot damage shells by introducing facets but processing time increases up to 2 weeks

Ozone mandrel removal

- Reduces processing temperature and preserves inner/outer surface quality but increases processing time up to 2 weeks
- Tumble finishing and ozone mandrel removal are promising processing methods that will likely increase yield and quality of capsules

